

## Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	$I_D$
100V	70mΩ@10V	10A
	85mΩ@4.5V	
-100V	230mΩ@-10V	-7A
	240mΩ@-4.5V	


**合肥矽普半导体**
*Siliup Semiconductor Technology Co.,Ltd*

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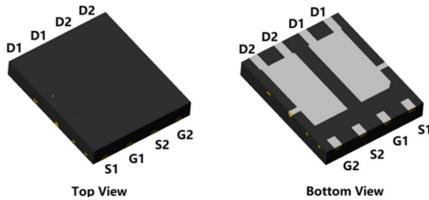
## Feature

- Fast switching speed
- Surface mount package
- ROHS Compliant & Halogen-Free
- 100% Single Pulse avalanche energy Test

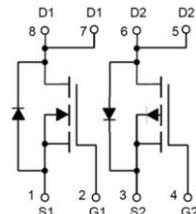
## Applications

- DC-DC Converters.
- Motor Control.

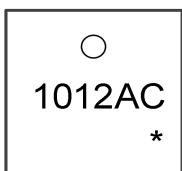
## Package


**PDFN5X6-8L**

## Circuit diagram



## Marking


 1012AC :Device Code  
 \* :Month Code

## Order Information

Device	Package	Unit/Tape
SP1012ACNK	PDFN5X6-8L	5000

**Absolute maximum ratings (Ta=25°C,unless otherwise noted)**

Parameter	Symbol	Rating		Unit
		N-Channel	P-Channel	
Drain-Source Voltage	V <sub>DS</sub>	100	-100	V
Gate-Source Voltage	V <sub>GS</sub>	±20	±20	V
Continuous Drain Current (Tc=25°C)	I <sub>D</sub>	10	-7	A
Pulse Drain Current Tested	I <sub>DM</sub>	40	-28	A
Single pulsed avalanche energy <sup>1</sup>	E <sub>AS</sub>	25	49	mJ
Power Dissipation (Tc=25°C)	P <sub>D</sub>	22		W
Thermal Resistance Junction-to-Case	R <sub>θJC</sub>	5.7		°C/W
Storage Temperature Range	T <sub>STG</sub>	-55 to 150		°C
Operating Junction Temperature Range	T <sub>J</sub>	-55 to 150		°C

**N-Electrical characteristics (Ta=25°C, unless otherwise noted)**

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	VGS=0V , ID=250uA	100	-	-	V
Drain-Source Leakage Current	I <sub>DSS</sub>	VDS=80V , VGS=0V , TJ=25°C	-	-	1	uA
Gate-Source Leakage Current	I <sub>GSS</sub>	VGS=±20V , VDS=0V	-	-	±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	VGS=VDS , ID =250uA	1.0	1.8	2.5	V
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	VGS = 10V, ID = 2A	-	70	88	mΩ
		VGS = 4.5V, ID = 1A	-	85	115	
<b>Dynamic characteristics</b>						
Input Capacitance	C <sub>iss</sub>	VDS=50V , VGS=0V , f=1MHz	-	792	-	pF
Output Capacitance	C <sub>oss</sub>		-	23	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		-	19	-	
Total Gate Charge	Q <sub>g</sub>	VDS=50V , VGS=10V , ID=3A	-	13.6	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	2.1	-	
Gate-Drain Charge	Q <sub>gd</sub>		-	1.9	-	
<b>Switching Characteristics</b>						
Turn-On Delay Time	T <sub>d(on)</sub>	VDD=50V VGS=10V , RG=3Ω, ID=3A	-	7	-	nS
Rise Time	T <sub>r</sub>		-	1.5	-	
Turn-Off Delay Time	T <sub>d(off)</sub>		-	15.3	-	
Fall Time	T <sub>f</sub>		-	2	-	
<b>Diode Characteristics</b>						
Diode Forward Voltage	V <sub>SD</sub>	VGS=0V , IS=1A , TJ=25°C	-	-	1.2	V
Maximum Body-Diode Continuous Current	I <sub>s</sub>		-	-	10	A
Reverse recover time	T <sub>rr</sub>	I <sub>s</sub> =10A, di/dt=100A/us, Tj=25°C	-	35	-	nS
Reverse recovery charge	Q <sub>rr</sub>		-	21	-	nC

**Note:**

1.The EAS Test condition is VDD=50V,VGS =10V,L = 0.5mH, Rg=25Ω

**P-Electrical characteristics (Ta=25°C, unless otherwise noted)**

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	VGS=0V , ID=-250uA	-100	-	-	V
Drain-Source Leakage Current	I <sub>DSS</sub>	VDS=-80V , VGS=0V , TJ=25°C	-	-	-1	uA
Gate-Source Leakage Current	I <sub>GSS</sub>	VGS=±20V , VDS=0V	-	-	±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	VGS=VDS , ID =-250uA	-1.0	-1.8	-2.5	V
Static Drain-Source On-Resistance	R <sub>Ds(on)</sub>	VGS =-10V, ID =-2A	-	230	290	mΩ
		VGS =-4.5V, ID =-1A	-	240	320	
<b>Dynamic characteristics</b>						
Input Capacitance	C <sub>iss</sub>	VDS=-50V , VGS=0V , f=1MHz	-	721	-	pF
Output Capacitance	C <sub>oss</sub>		-	30	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		-	18	-	
Total Gate Charge	Q <sub>g</sub>	VDS=-50V , VGS=-10V , ID=-3A	-	16	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	3	-	
Gate-Drain Charge	Q <sub>gd</sub>		-	2.5	-	
<b>Switching Characteristics</b>						
Turn-On Delay Time	T <sub>d(on)</sub>	VDD=-50V VGS=-10V , RG=6Ω, ID=-3A	-	9	-	nS
Rise Time	T <sub>r</sub>		-	6.5	-	
Turn-Off Delay Time	T <sub>d(off)</sub>		-	28	-	
Fall Time	T <sub>f</sub>		-	7.5	-	
<b>Diode Characteristics</b>						
Diode Forward Voltage	V <sub>SD</sub>	VGS=0V , IS=-1A , TJ=25°C	-	-	-1.2	V
Maximum Body-Diode Continuous Current	I <sub>S</sub>		-	-	-7	A
Reverse recover time	T <sub>rr</sub>	I <sub>S</sub> =-7A, di/dt=-100A/us, Tj=25°C	-	32	-	nS
Reverse recovery charge	Q <sub>rr</sub>		-	47	-	nC

**Note:**

1.The EAS Test condition is VDD=-50V,VGS =-10V,L = 0.5mH, Rg=25Ω



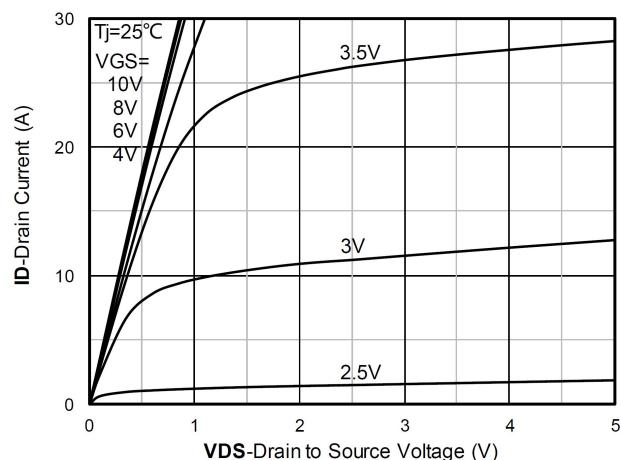
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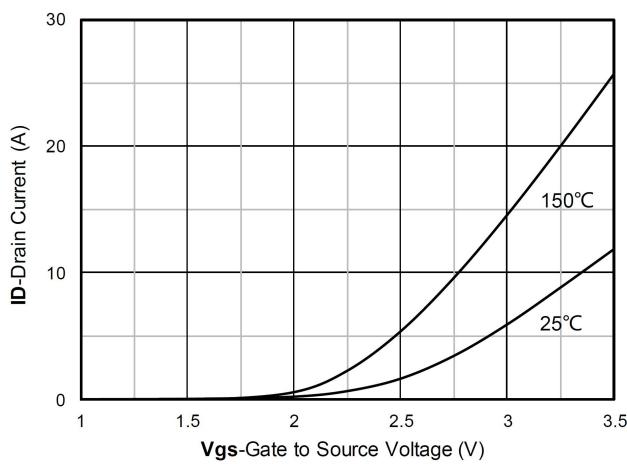
SP1012ACNK

100V Complementary MOSFET

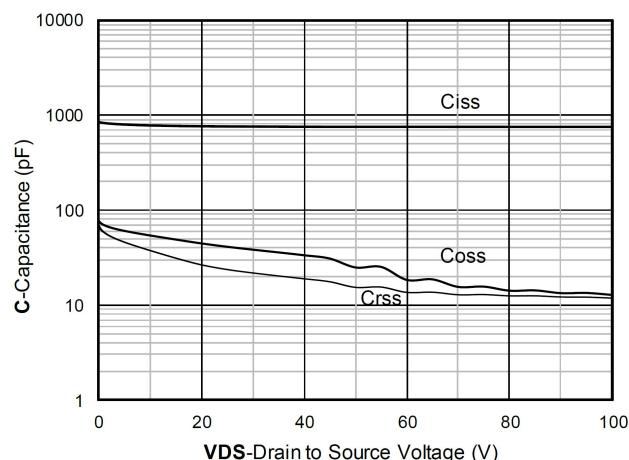
## N-Channel Typical Characteristics



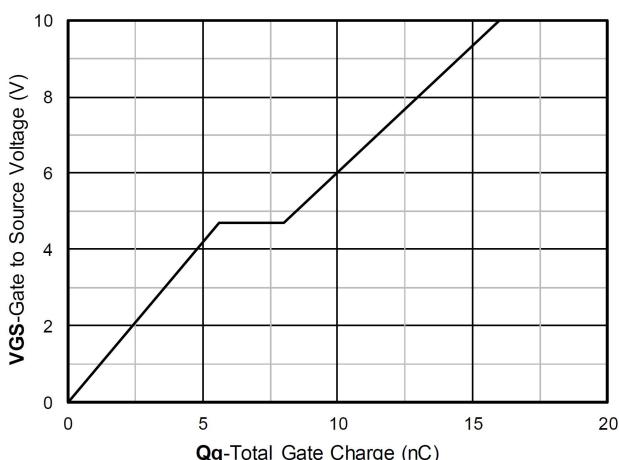
Output Characteristics



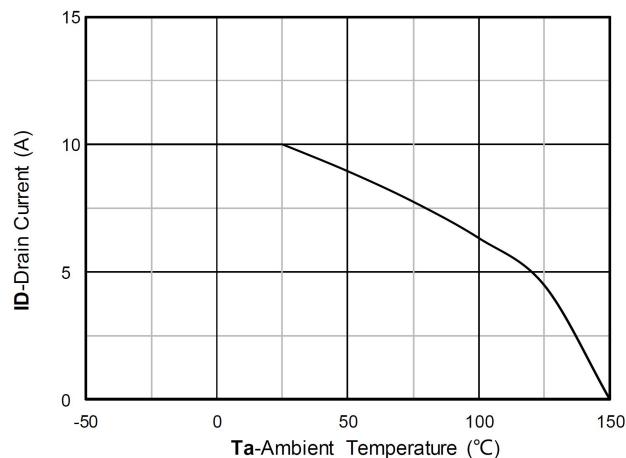
Transfer Characteristics



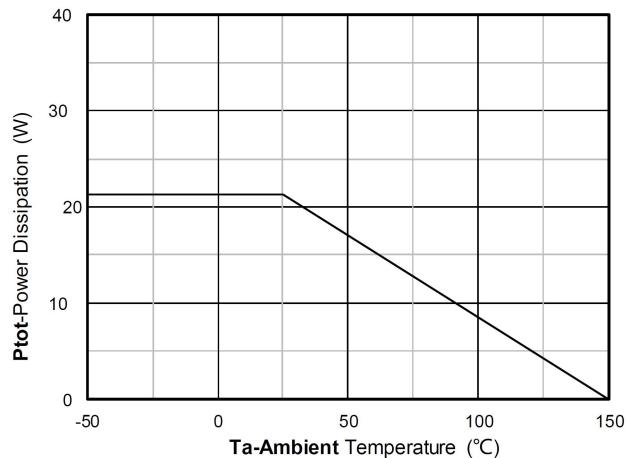
Capacitance Characteristics



Gate Charge



Current dissipation



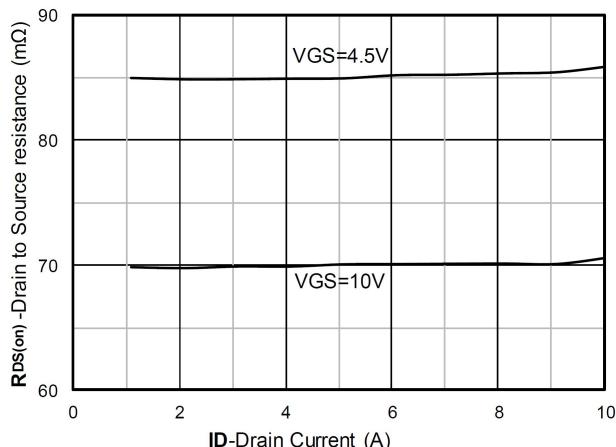
Power dissipation



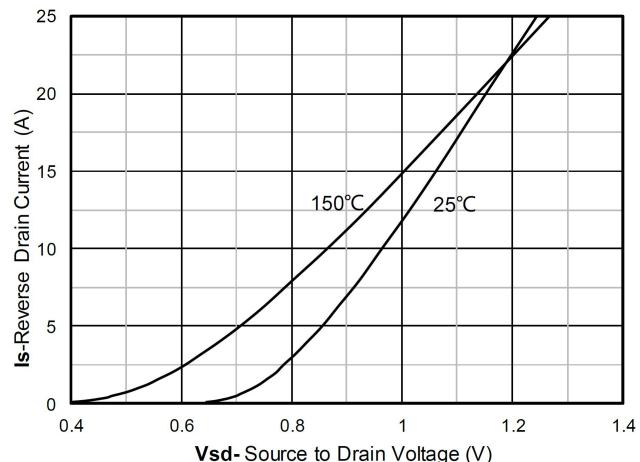
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**SP1012ACNK**

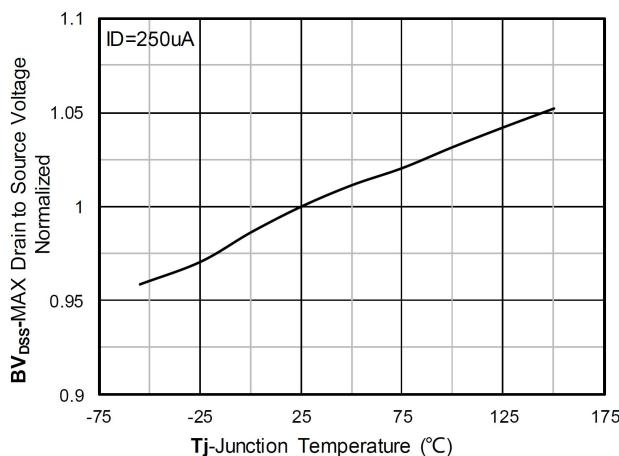
**100V Complementary MOSFET**



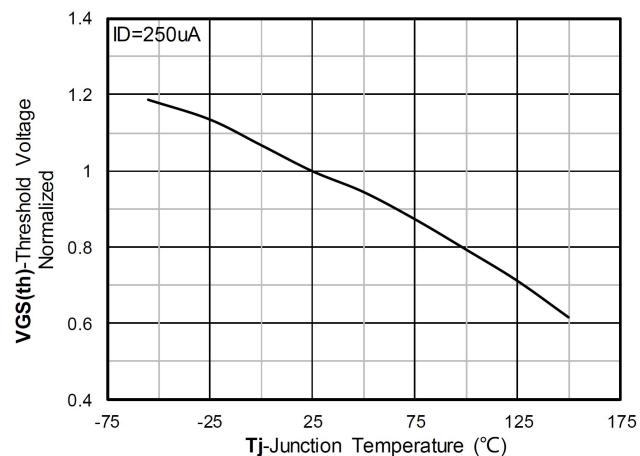
R<sub>D5(on)</sub> VS Drain Current



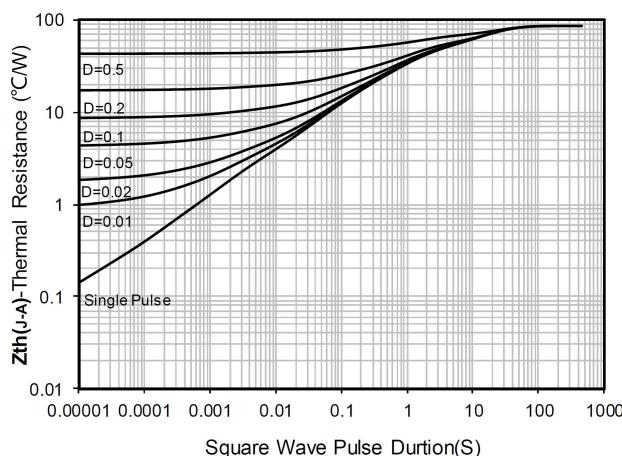
Forward characteristics of reverse diode



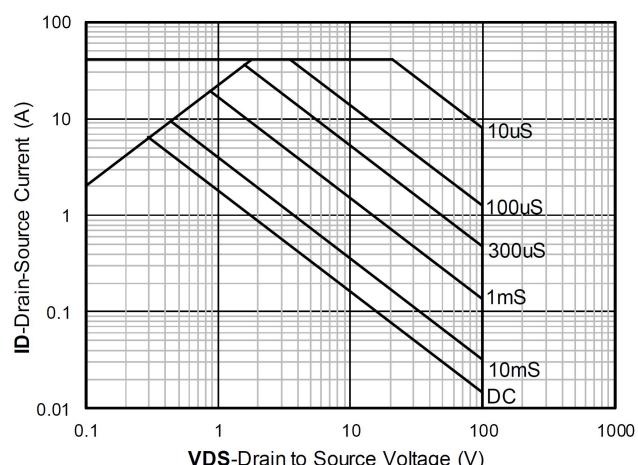
Normalized breakdown voltage



Normalized Threshold voltage



Maximum Transient Thermal Impedance



Safe Operation Area



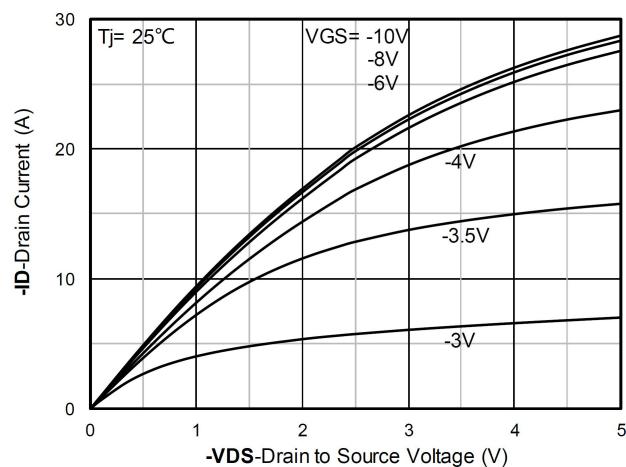
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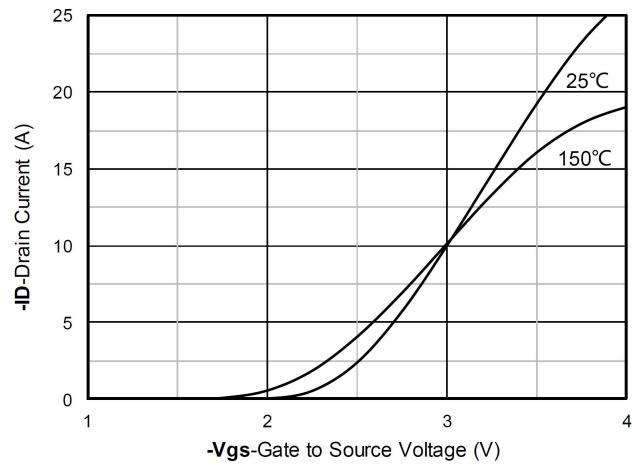
SP1012ACNK

100V Complementary MOSFET

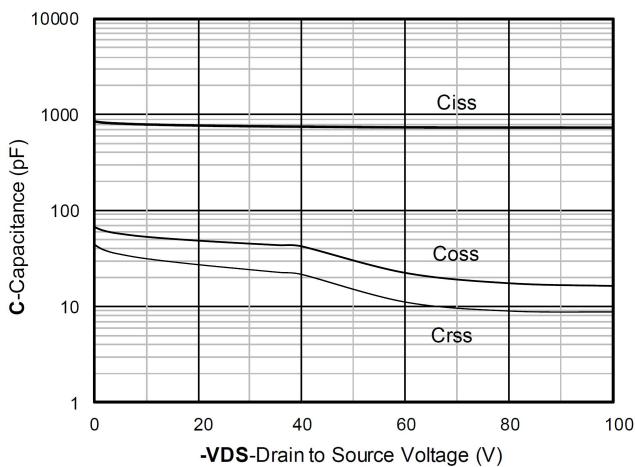
## P-Channel Typical Characteristic



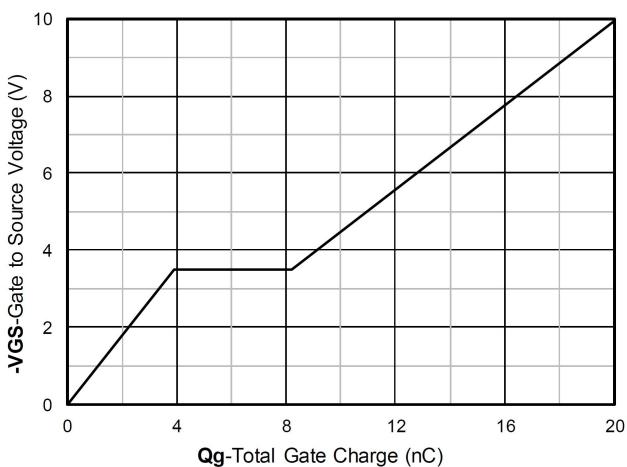
Output Characteristics



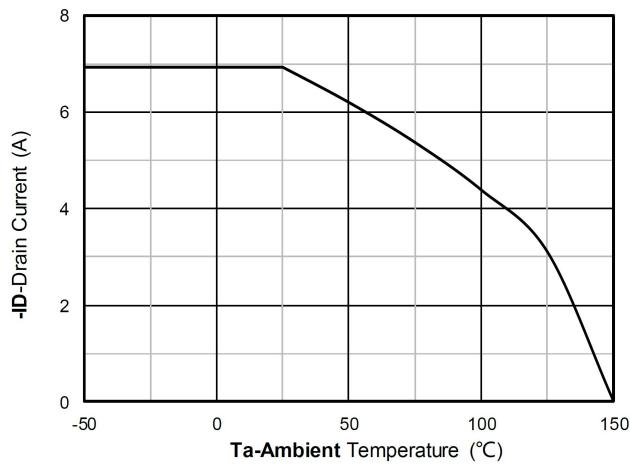
Transfer Characteristics



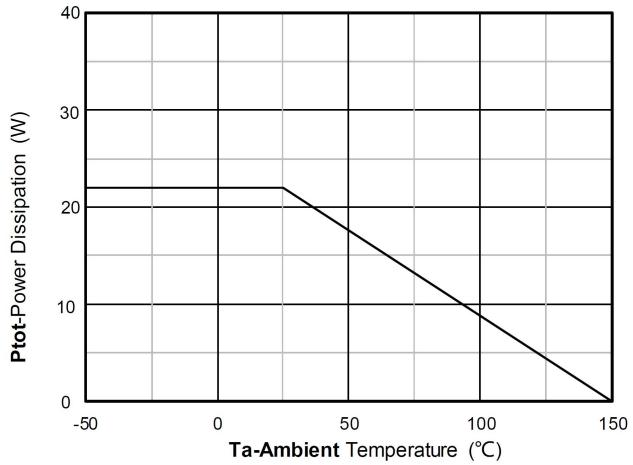
Capacitance Characteristics



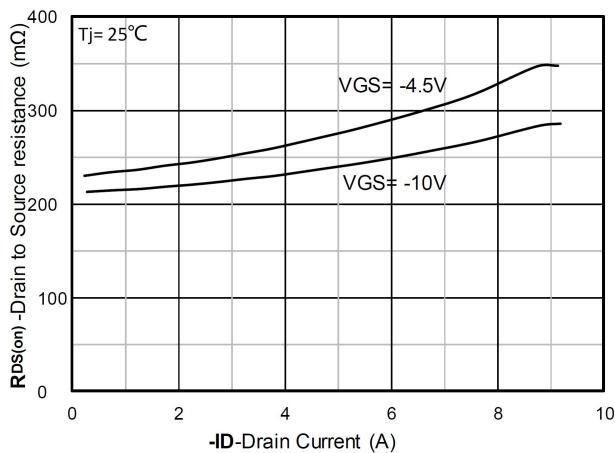
Gate Charge



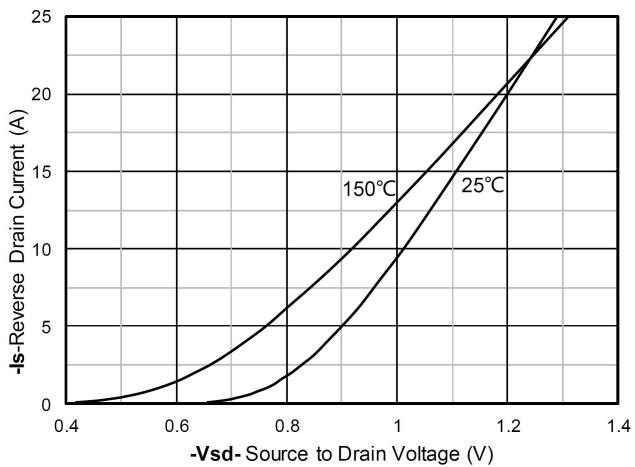
Current dissipation



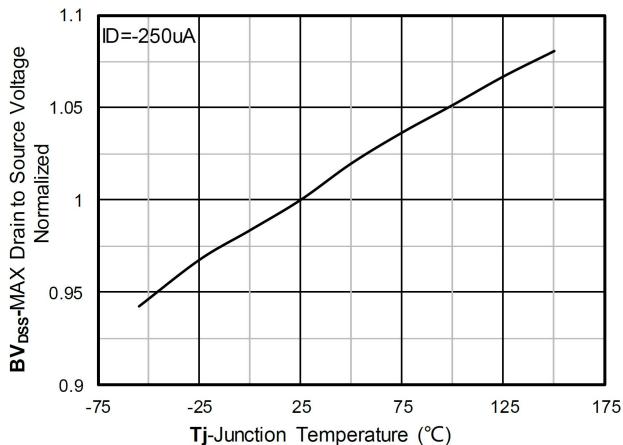
Power dissipation



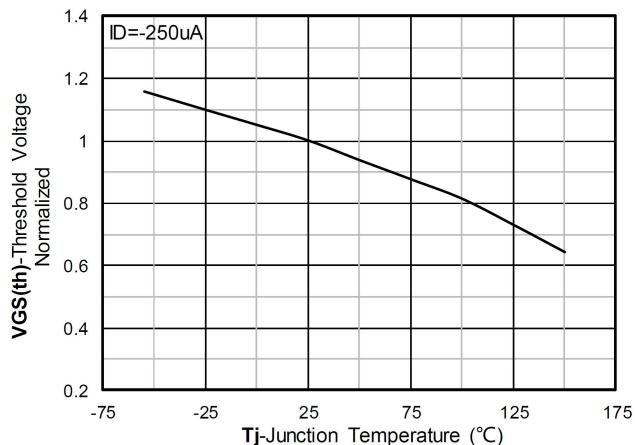
R<sub>DS(on)</sub> VS Drain Current



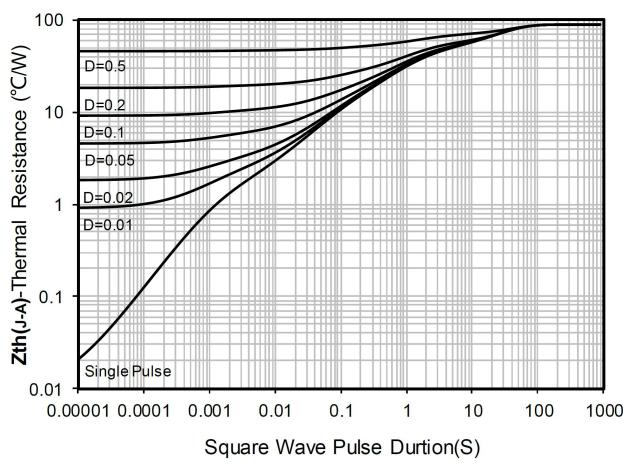
Forward characteristics of reverse diode



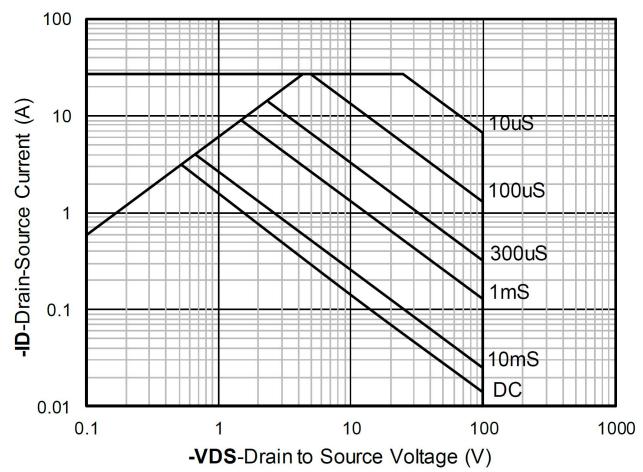
Normalized breakdown voltage



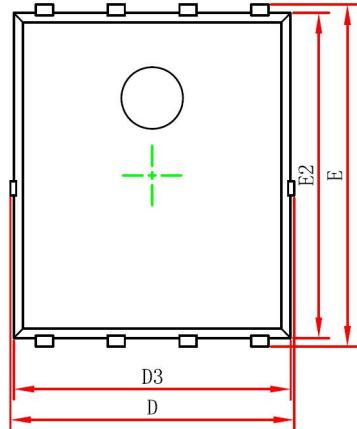
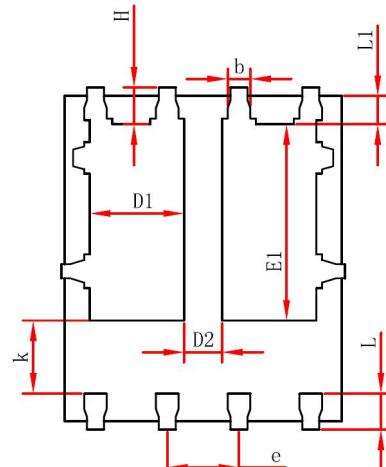
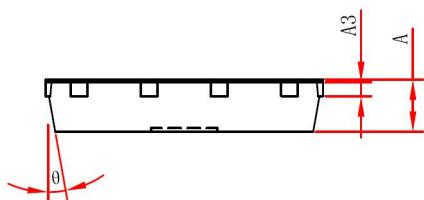
Normalized Threshold voltage



Maximum Transient Thermal Impedance



Safe Operation Area

**PDFN5X6-8L Package Information**

Top View  
 [顶视图]

Bottom View  
 [背视图]

Side View  
 [侧视图]

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.254 REF.			0.010REF.
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	1.470	1.870	0.058	0.074
D2	0.470	0.870	0.019	0.034
E1	3.375	3.575	0.133	0.141
D3	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
e	1.270TYP.		0.050TYP.	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
H	0.574	0.726	0.023	0.029
θ	10°	12°	10°	12°